



bestirpower

# BCBF120N21M1

## N-Channel Silicon Carbide Power MOSFET

1200 V, 100 A, 21 mΩ

### Features

- High switching speed with a low gate charge
- Fast intrinsic diode with low reverse recovery
- Robust Avalanche Capability
- 100% Avalanche Tested
- Pb-free, Halogen Free, and RoHS Compliant

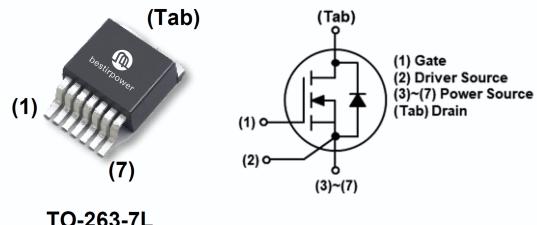
$BV_{DSS, T_c=25^\circ C}$	$I_{D, T_c=25^\circ C}$	$R_{DS(on), typ}$	$Q_{g, typ}$
1200 V	100 A	21 mΩ	198 nC

### Benefits

- System efficiency improvement
- Higher frequency applicability
- Increased power density
- Reduced cooling effort

### Applications

- Solar inverter
- EV charging station
- UPS
- Industrial power supply



TO-263-7L



### Absolute Maximum Ratings ( $T_J = 25^\circ C$ unless otherwise noted)

Symbol	Parameter		Value	Unit
$V_{DSS}$	Drain to Source Voltage		1200	V
$V_{GS}$	Gate to Source Voltage (DC)		-10 / +22	V
$V_{GSop}$	Recommended Operation Value		-5 / +18	V
$I_D$	Drain Current	$V_{GS} = 18 V, (T_c = 25^\circ C)$	100	A
		$V_{GS} = 18 V, (T_c = 100^\circ C)$	71	
$I_{DM}$	Drain Current	Pulsed (Note1)	250	A
$P_D$	Power Dissipation	$(T_c = 25^\circ C)$	469	W
		Derate Above 25°C	3.1	W/°C
$T_J, T_{STG}$	Operating and Storage Temperature Range		-55 to 175	°C

※Note 1 : Limited by maximum junction temperature.

### Thermal Characteristics

Symbol	Parameter	Value	Unit
$R_{\theta JC}$	Thermal Resistance, Junction to Case, Max.	0.32	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient, Max.	40	
$T_{sold}$	Soldering temperature, wave soldering only allowed at leads	260	°C

**Electrical Characteristics** ( $T_J = 25^\circ\text{C}$  unless otherwise noted)

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
<b>Off Characteristics</b>						
$\text{BV}_{\text{DSS}}$	Drain to Source Breakdown Voltage	$V_{\text{GS}} = 0 \text{ V}, I_D = 1 \text{ mA}$	1200	-	-	V
$I_{\text{DS}(\text{S})}$	Zero Gate Voltage Drain Current	$V_{\text{DS}} = 1200 \text{ V}, V_{\text{GS}} = 0 \text{ V}$	-	1	100	$\mu\text{A}$
		$V_{\text{DS}} = 1200 \text{ V}, V_{\text{GS}} = 0 \text{ V}, T_J = 175^\circ\text{C}$	-	10	-	
$I_{\text{GSS}}$	Gate-Source Leakage Current	$V_{\text{GS}} = +22 \text{ V}, V_{\text{DS}} = 0 \text{ V}$	-	-	+100	$\text{nA}$
		$V_{\text{GS}} = -10 \text{ V}, V_{\text{DS}} = 0 \text{ V}$	-	-	-100	

**On Characteristics**

$V_{\text{GS}(\text{th})}$	Gate Threshold Voltage	$V_{\text{GS}} = V_{\text{DS}}, I_D = 17 \text{ mA}$ (tested after $V_{\text{GS}} = 22 \text{ V}, 1 \text{ ms pulse}$ )	2.0	3.0	4.5	V
$R_{\text{DS}(\text{on})}$	Static Drain to Source On Resistance	$V_{\text{GS}} = 18 \text{ V}, I_D = 50 \text{ A}$	-	21	29.4	$\text{m}\Omega$
		$V_{\text{GS}} = 18 \text{ V}, I_D = 50 \text{ A}, T_J = 175^\circ\text{C}$	-	33.6	-	
$g_{\text{fs}}$	Transconductance	$V_{\text{DS}} = 20 \text{ V}, I_D = 50 \text{ A}$	-	24.4	-	S

**Dynamic Characteristics**

$C_{\text{iss}}$	Input Capacitance	$V_{\text{DS}} = 800 \text{ V}, V_{\text{GS}} = 0 \text{ V}, f = 250 \text{ kHz}$	-	3741	-	$\text{pF}$
$C_{\text{oss}}$	Output Capacitance		-	224	-	
$C_{\text{rss}}$	Reverse Capacitance		-	17	-	
$E_{\text{oss}}$	Stored Energy in Output Capacitance	$V_{\text{DS}} = 0 \text{ V to } 800 \text{ V}, V_{\text{GS}} = 0 \text{ V}$	-	93	-	$\mu\text{J}$
$C_{\text{o(er)}}$	Energy Related Output Capacitance		-	291	-	
$C_{\text{o(tr)}}$	Time Related Output Capacitance		-	456	-	
$Q_{\text{g(tot)}}$	Total Gate Charge	$V_{\text{DS}} = 800 \text{ V}, I_D = 50 \text{ A}, V_{\text{GS}} = -5 \text{ V / } 18 \text{ V, Inductive load}$	-	198	-	$\text{nC}$
$Q_{\text{gs}}$	Gate to Source Charge		-	48	-	
$Q_{\text{gd}}$	Gate to Drain "Miller" Charge		-	65	-	
$R_G$	Internal Gate Resistance	$f = 1 \text{ MHz open drain}$	-	3.0	-	$\Omega$

**Switching Characteristics**

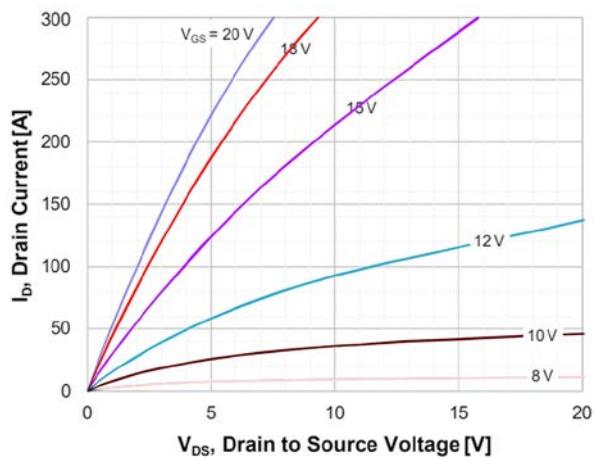
$t_{\text{d(on)}}$	Turn-On Delay Time	$V_{\text{DS}} = 800 \text{ V}, I_D = 50 \text{ A}, V_{\text{GS}} = -5 \text{ V / } 18 \text{ V, } R_G = 2 \Omega, \text{ FWD : BCH120S020D1, Inductive load}$	-	29	-	$\text{ns}$
$t_r$	Turn-On Rise Time		-	29	-	
$t_{\text{d(off)}}$	Turn-Off Delay Time		-	62	-	
$t_f$	Turn-Off Fall Time		-	12	-	
$E_{\text{on}}$	Turn-on Switching Energy		-	477	-	
$E_{\text{off}}$	Turn-off Switching Energy		-	342	-	
$E_{\text{tot}}$	Total Switching Energy		-	819	-	

**Source-Drain Diode Characteristics**

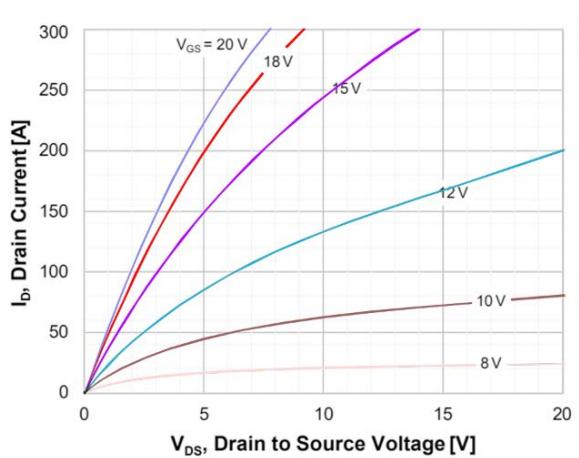
$I_S$	Maximum Continuous Diode Forward Current	$V_{\text{GS}} = -5 \text{ V, } I_{\text{SD}} = 50 \text{ A}$	-	-	100	$\text{A}$
$I_{\text{SM}}$	Maximum Pulsed Diode Forward Current		-	-	250	
$V_{\text{SD}}$	Diode Forward Voltage	$V_{\text{DD}} = 800 \text{ V, } I_{\text{SD}} = 50 \text{ A, } dI_F/dt = 3000 \text{ A}/\mu\text{s, Includes } Q_{\text{oss}}$	-	4.2	-	$\text{V}$
$t_{\text{rr}}$	Reverse Recovery Time		-	22	-	
$Q_{\text{rr}}$	Reverse Recovery Charge	$dI_F/dt = 3000 \text{ A}/\mu\text{s, Includes } Q_{\text{oss}}$	-	482	-	$\text{nC}$
			-	-	-	

## Typical Performance Characteristics

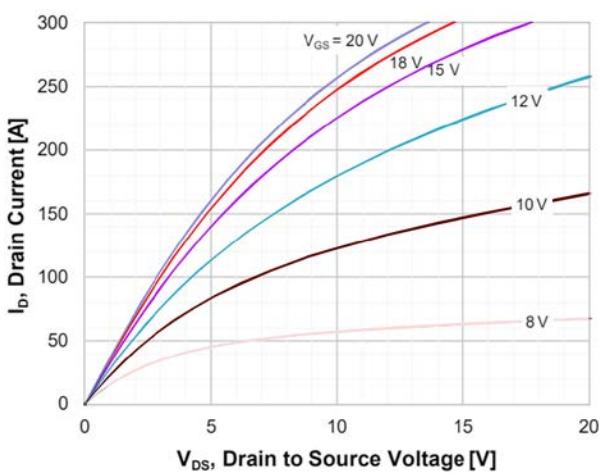
**Figure 1. On-Region Characteristics  $T_J = -40^\circ\text{C}$**



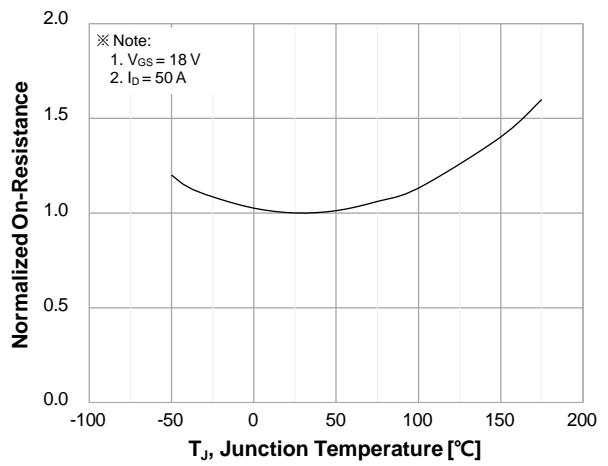
**Figure 2. On-Region Characteristics  $T_J = 25^\circ\text{C}$**



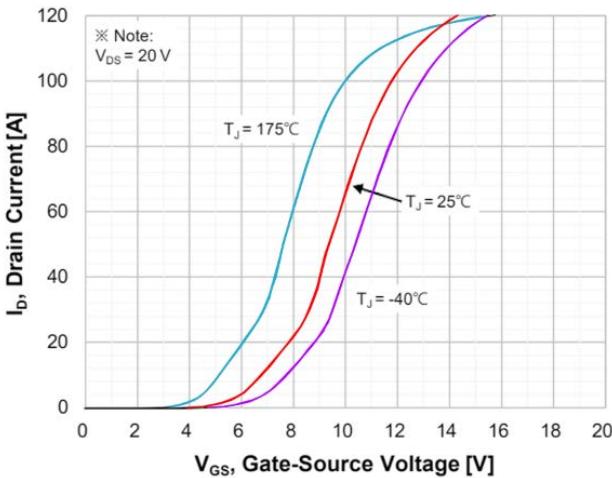
**Figure 3. On-Region Characteristics  $T_J = 175^\circ\text{C}$**



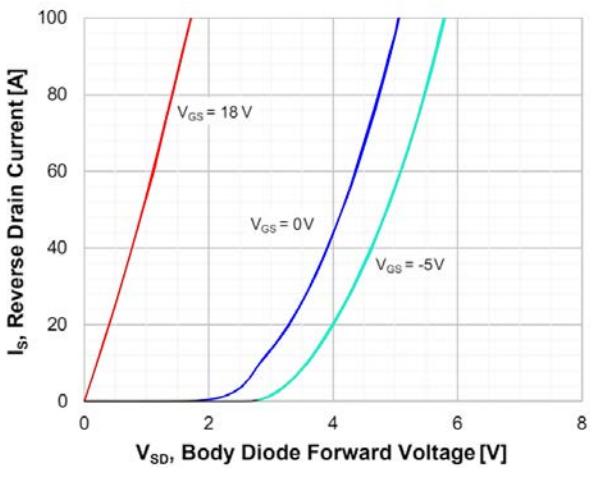
**Figure 4. Normalized On-Resistance Characteristics vs. Temperature**



**Figure 5. Transfer Characteristics**

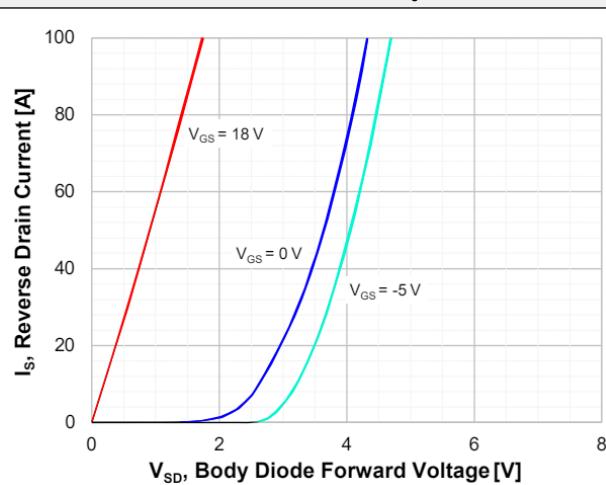


**Figure 6. Diode Forward Voltage Characteristics vs. Source-Drain Current  $T_J = -40^\circ\text{C}$**

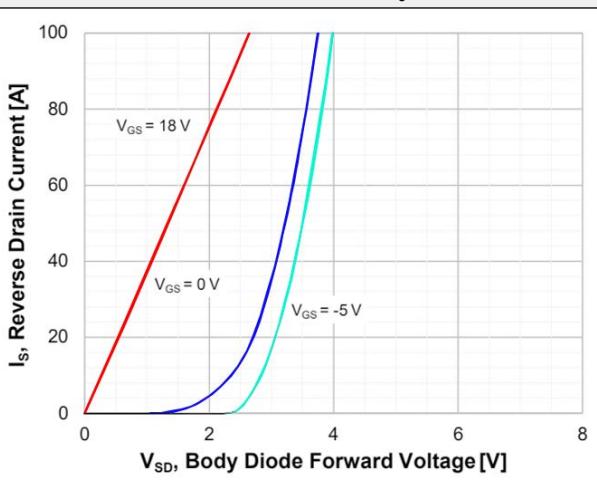


## Typical Performance Characteristics

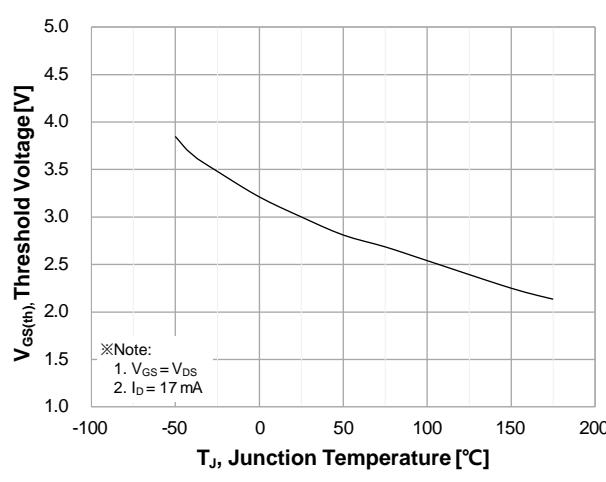
**Figure 7. Diode Forward Voltage Characteristics vs. Source-Drain Current  $T_J = 25^\circ\text{C}$**



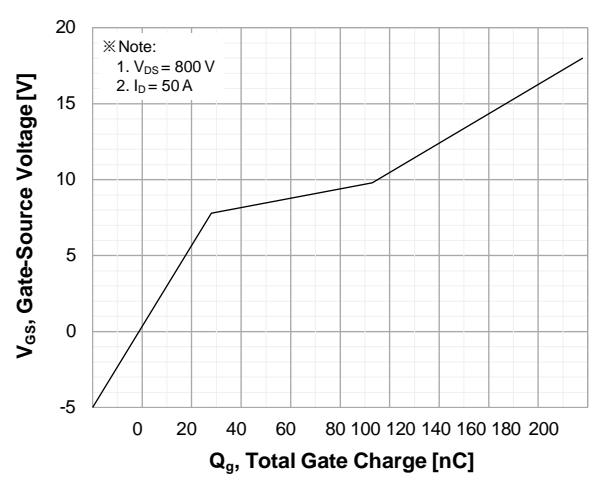
**Figure 8. Diode Forward Voltage Characteristics vs. Source-Drain Current  $T_J = 175^\circ\text{C}$**



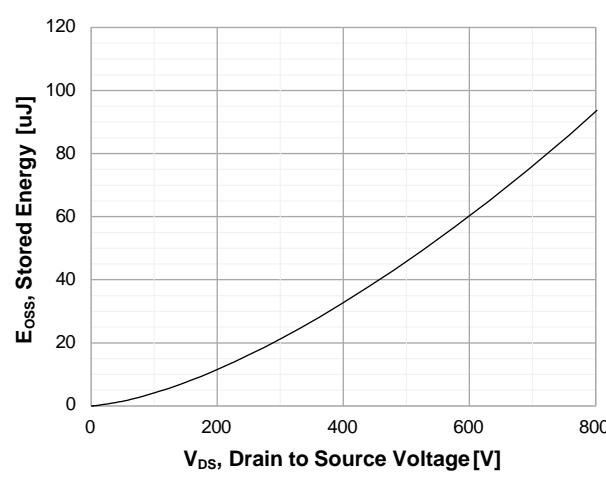
**Figure 9. Threshold Voltage vs. Temperature**



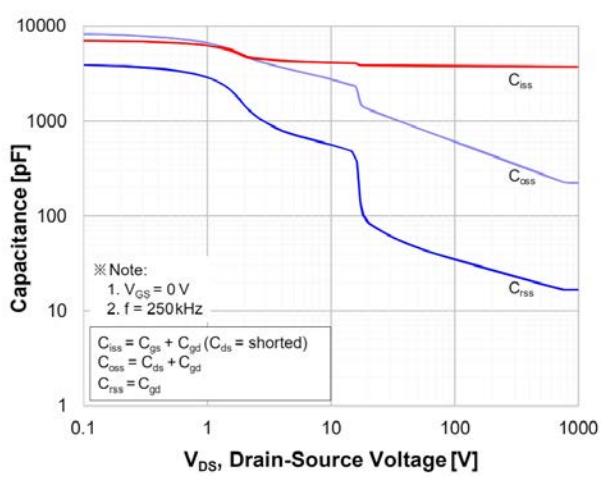
**Figure 10. Gate Charge Characteristics**



**Figure 11. Stored Energy in Output Capacitance**

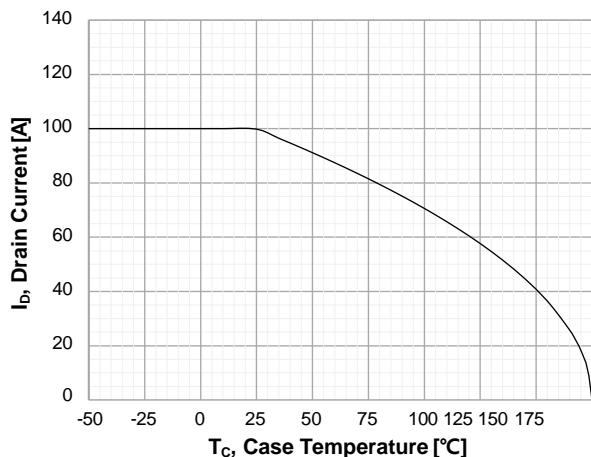


**Figure 12. Capacitance Characteristics**

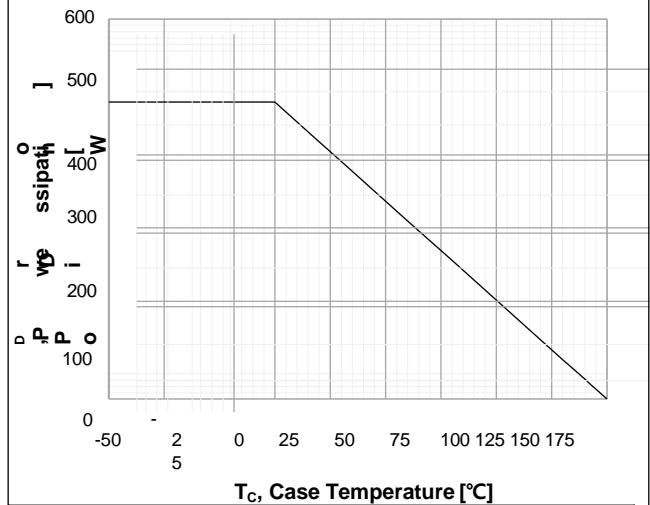


## Typical Performance Characteristics

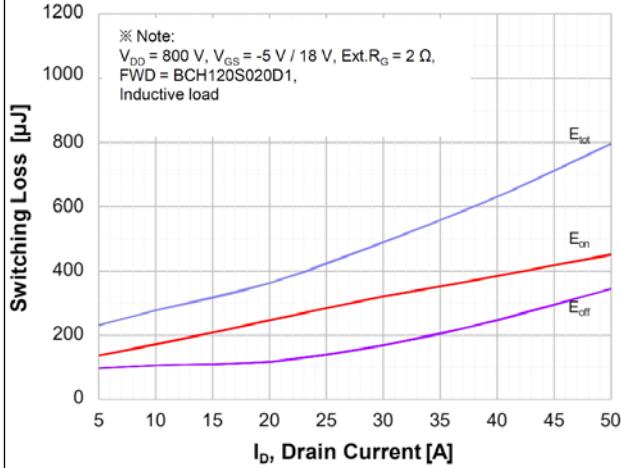
**Figure 13. Continuous Drain Current Derating vs. Case Temperature**



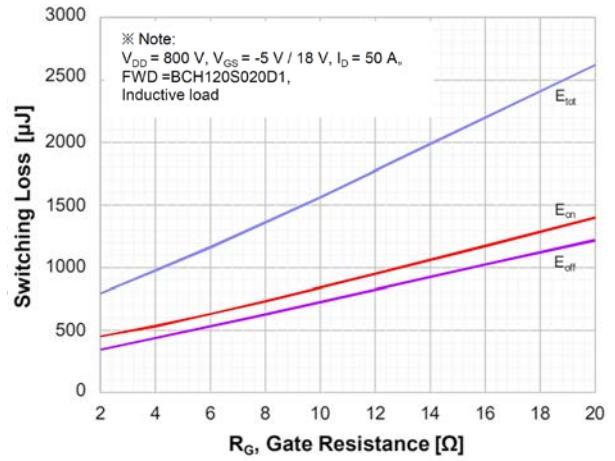
**Figure 14. Maximum Power Dissipation Derating vs. Case Temperature**



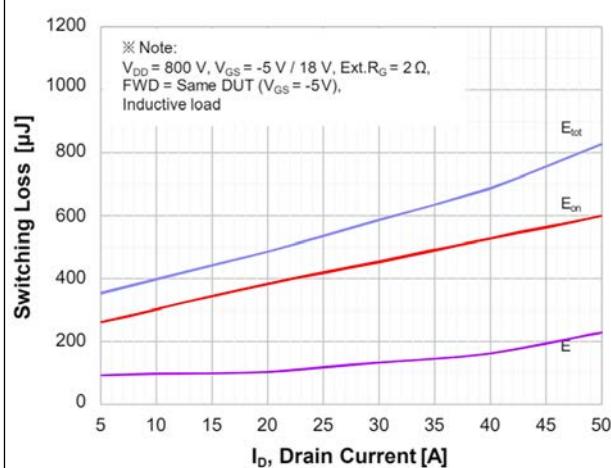
**Figure 15. Typ. Switching Losses vs. Drain Current**



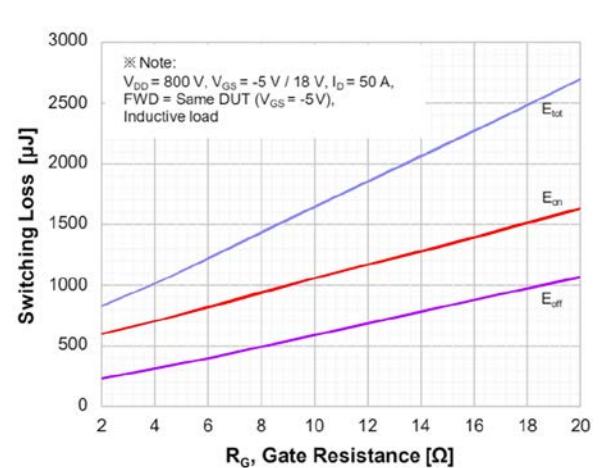
**Figure 16. Typ. Switching Losses vs. Gate Resistance**



**Figure 17. Typ. Switching Losses vs. Drain Current**

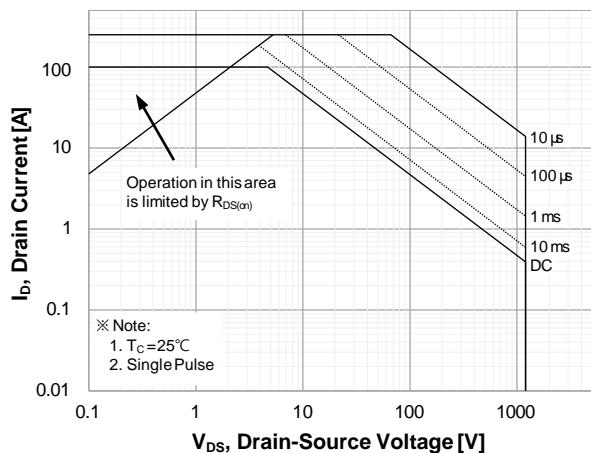


**Figure 18. Typ. Switching Losses vs. Gate Resistance**

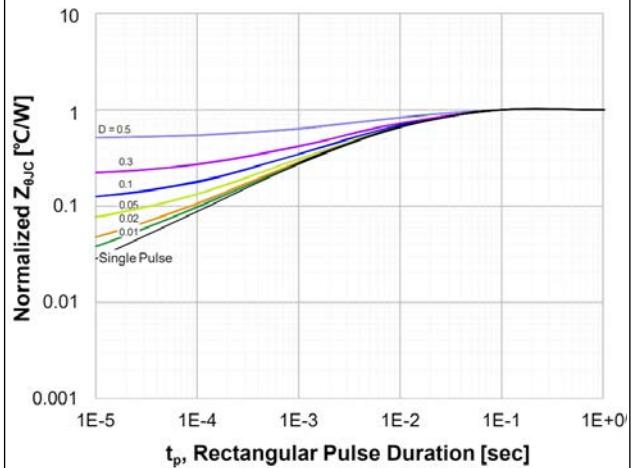


## Typical Performance Characteristics

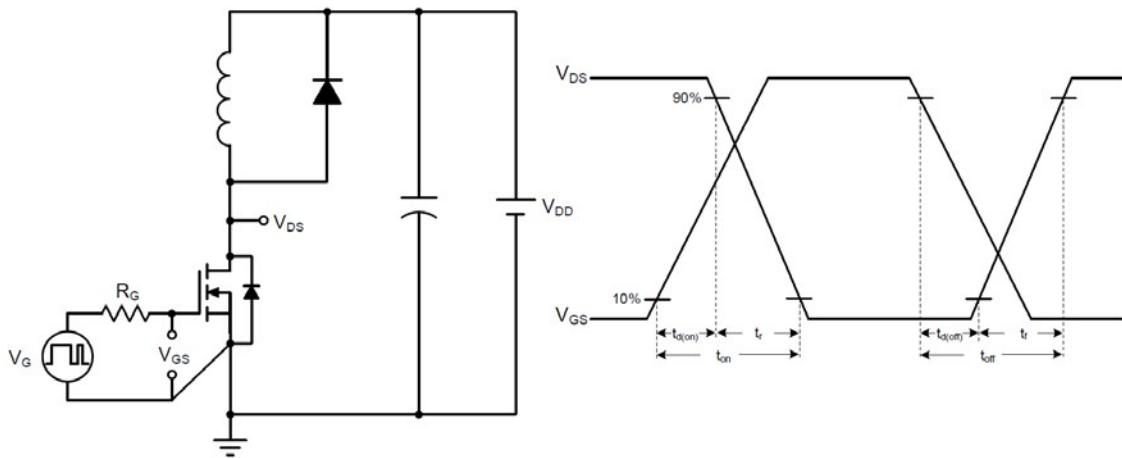
**Figure 19. Maximum Safe Operating Area**



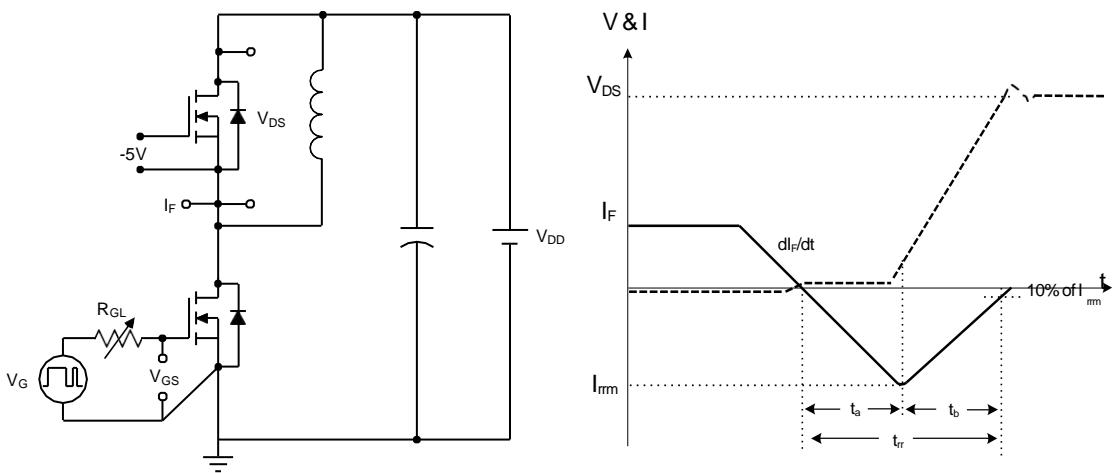
**Figure 20. Transient Thermal Response Curve**



**Figure 21. Inductive Load Switching Test Circuit and Waveforms**

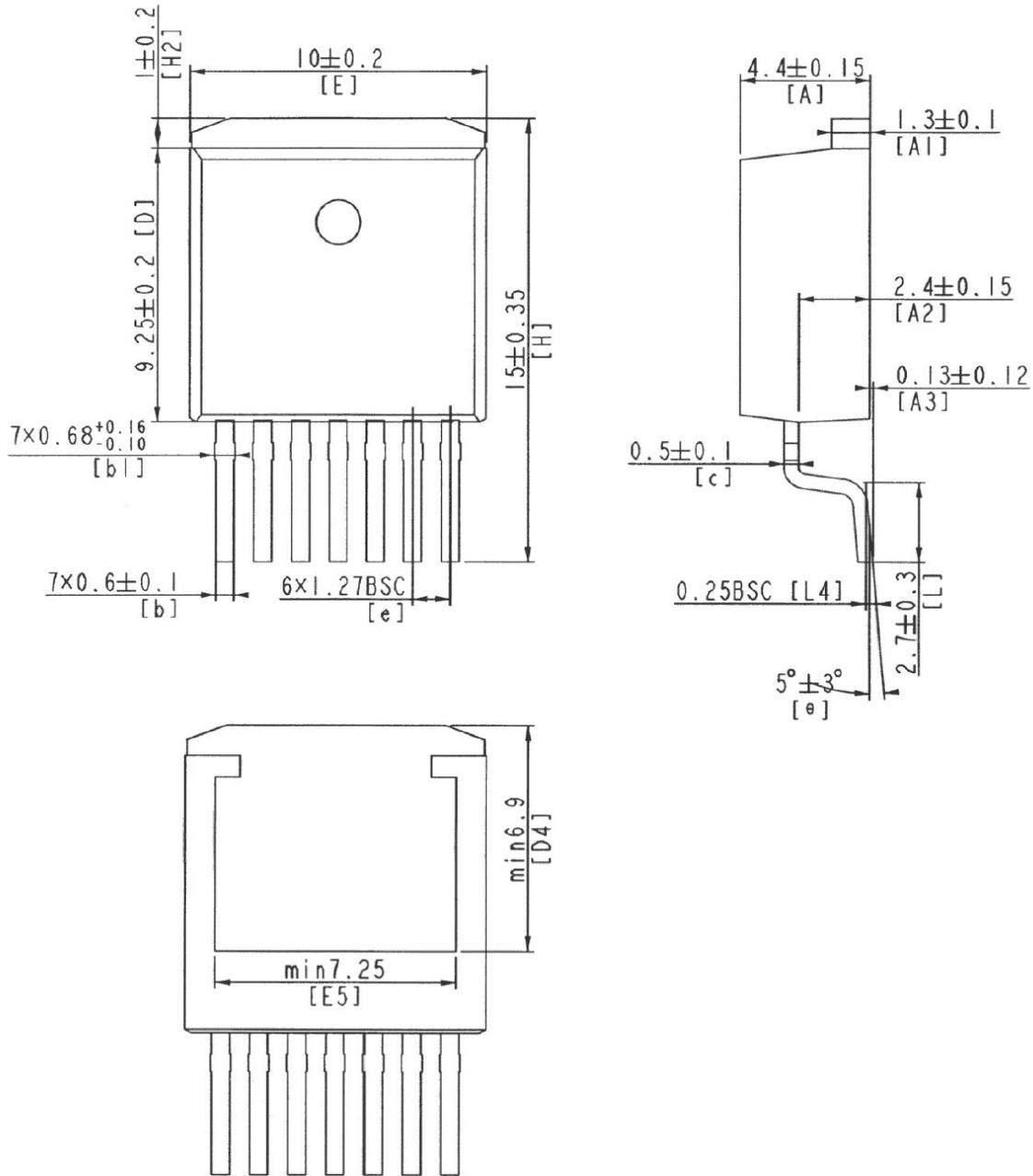


**Figure 22. Peak Diode Recovery dv/dt Test Circuit and Waveforms**



## Package Outlines

# TO263-7L



\* Dimensions in millimeters

**Package Marking and Ordering Information**

Part Number	Top Marking	Package	Packing Method	Quantity
BCBF120N21M1	BCBF120N21M1	TO263-7L	Tape & Reel	800 units

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